



# Erratum

## Erratum: “Solder Joint Shape Prediction Using a Modified Perzyna Viscoplastic Model” [Journal of Electronic Packaging, 2005, 127(3), pp. 290–298]

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Part (c) of Fig. 6 was inadvertently deleted from the final paper and is reproduced here. The on-line version of the paper has been revised.

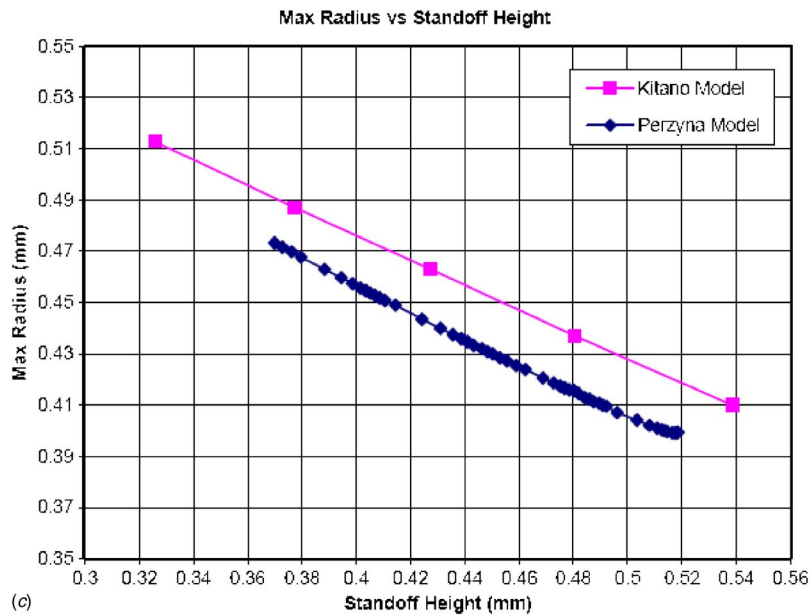


Fig. 6c